

Condensation Reflow Soldering Machine

For laboratory, prototyping and small production

VP-MINI



Description

The machine is designed for reflow soldering laboratory and prototype, single pieces and small quantities PCB' s. Components such as QFPs, BGAs, Flip-Chips as well as hybrids are processed defect free with highest quality results.

Due the small size of the system it may be used at any place.

Its simple fast set up ensures a rapid ready for use providing the ability to solder high quality assemblies defect free.

Features

- Table model Top loader
- Window to observe the soldering process
- Suitable for BGA's, Stacked Packages,...
- Oxygen Free Soldering
- Homogeneous temperature transmission on the complete assembly
- No overheating of components

Energy supply	(Single Phase + Neutral + Ground) 220-240 Volt / 50-60 Hz
Power drawn	1.000 Watt (ca. 5 A)
System dimensions.	400 x 315 x 305 mm (L x W x H)
max. solder product format	240 x 170 x 20 mm (L x W x H)
Standard cycle time	ca. 10 Min
Soldering time	ca. 60 – 120 Seconds (depends on products)
Process temperature	(depends on medium type) 210 up to 240 °C
Weight	ca. 6 kg
Cooling	Forced air cooling
Heat transfer medium	GALDEN with the correct boiling temperature (max. 240 °C)
Medium basic filling quantity	ca. 450– 500 ml GALDEN

Technical changes reserved